

Long life recoil type meeting more compact and low-profile needs



Typical Specifications

Items		Specifications
Rating (max.)/(min.) (Resistive load)		10mA 5V DC / 50μA 3V DC
Contact resistance (Initial performance / After lifetime)		200mΩ max. / 500mΩ max.
Operating force		1N (Recoil side) 1.5N (Lock side)
Operating life	Without load	100,000 cycles (Recoil side) 30,000 cycles (Lock side)
	With load	100,000 cycles (Recoil side) 30,000 cycles (Lock side) (10mA 5V DC)

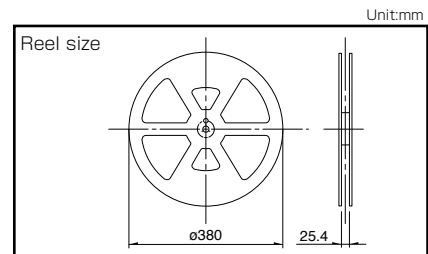
Product Line

Travel (mm)	Operating section directions	Poles	Positions	Changeover timing	Soldering	Operating	Shape of flame leg	Location lug	Minimum order unit (pcs.)		Products No.	Drawing No.		
									Japan	Export				
1.5	Horizontal	1	3	Not specified	Reflow	Left-side recoil	For PC board insert	Without	4,000	16,000		SSAG130100	1	
								With						SSAG130200
							Flat	Without				2	SSAG130300	
								With						SSAG130400
							Right-side recoil	For PC board insert				Without	3	
												With		SSAG230200
						Flat		Without	4	SSAG230300				
								With			SSAG230400			
						Double-side recoil		For PC board insert	Without	5		SSAG330100		
									With		SSAG330200			
							Flat	Without	6			SSAG330300		
								With			SSAG330400			

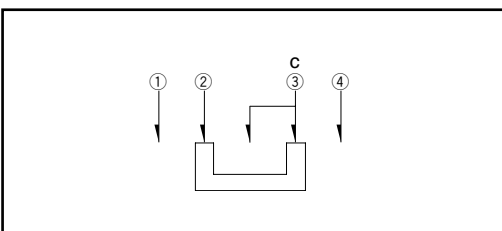
Packing Specifications

Taping

Number of packages (pcs.)			Tape width (mm)	Export package measurements (mm)
1 reel	1 case /Japan	1 case /export packing		
4,000	8,000	16,000	24	428×413×172

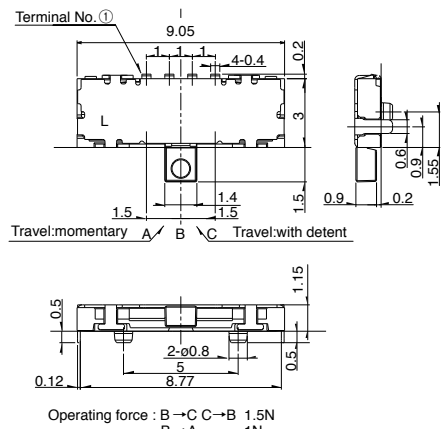
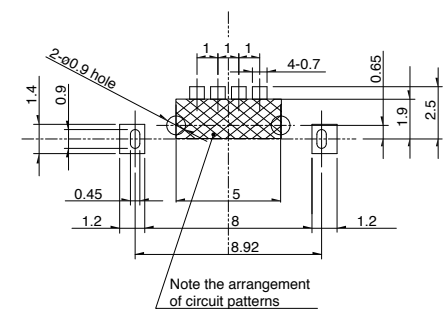
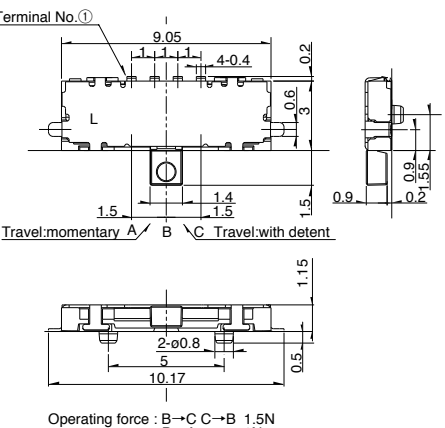
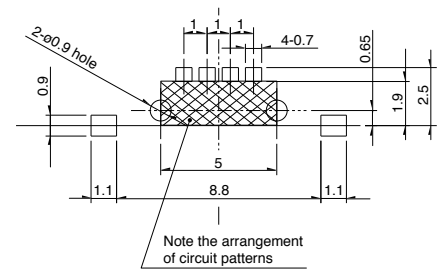
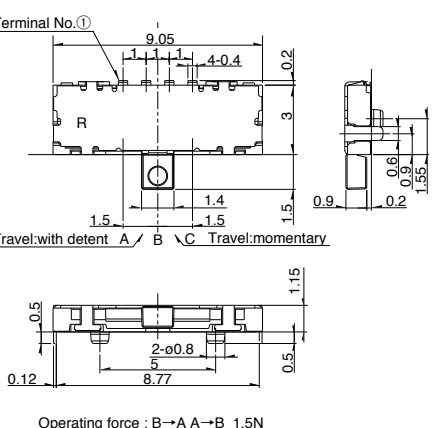
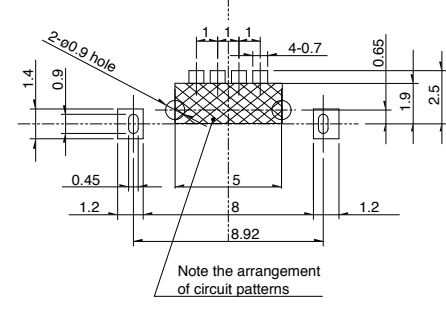


Circuit Diagram (Viewed from Direction A)



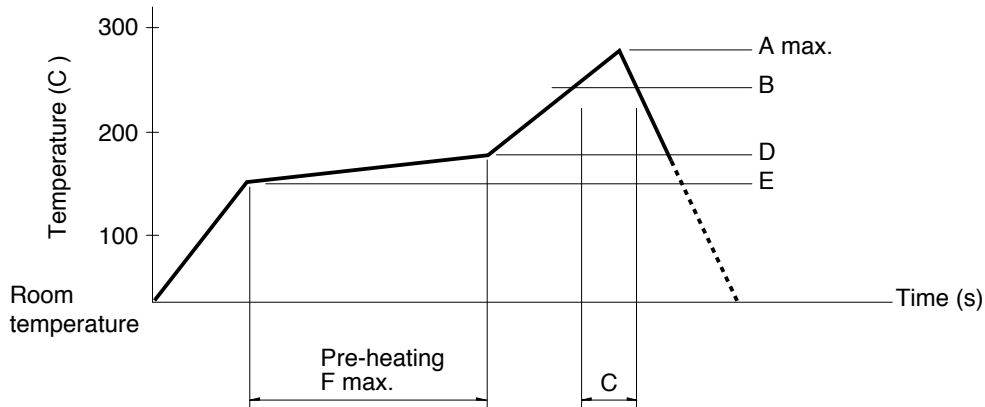
Dimensions

Unit:mm

No.	Style	PC board mounting hole and land dimensions (Viewed from the direction A)
1	<p>With boss</p>  <p>Terminal No.①</p> <p>9.05 4-0.4 0.2</p> <p>1.5 1.4 1.5 1.5 0.9 0.6 0.9 1.55 0.2</p> <p>Travel:momentary A / B \ C Travel:with detent</p> <p>0.5 1.15 0.12 8.77 5 2-φ0.8 0.5</p> <p>Operating force : B → C C → B 1.5N B → A 1N</p>	 <p>2-φ0.9 hole</p> <p>1.4 0.9 1 1 4-0.7 0.65 1.9 2.5</p> <p>0.45 5 8 1.2 8.92</p> <p>Note the arrangement of circuit patterns</p>
2	<p>With boss</p>  <p>Terminal No.①</p> <p>9.05 4-0.4 0.2</p> <p>1.5 1.4 1.5 1.5 0.9 0.6 0.9 1.55 0.2</p> <p>Travel:momentary A / B \ C Travel:with detent</p> <p>0.5 1.15 10.17 5 2-φ0.8 0.5</p> <p>Operating force : B → C C → B 1.5N B → A 1N</p>	 <p>2-φ0.9 hole</p> <p>0.9 1 1 4-0.7 0.65 1.9 2.5</p> <p>1.1 5 8.8 1.1</p> <p>Note the arrangement of circuit patterns</p>
3	<p>With boss</p>  <p>Terminal No.①</p> <p>9.05 4-0.4 0.2</p> <p>1.5 1.4 1.5 1.5 0.9 0.6 0.9 1.55 0.2</p> <p>Travel:with detent A / B \ C Travel:momentary</p> <p>0.5 1.15 0.12 8.77 5 2-φ0.8 0.5</p> <p>Operating force : B → A A → B 1.5N B → C 1N</p>	 <p>2-φ0.9 hole</p> <p>1.4 0.9 1 1 4-0.7 0.65 1.9 2.5</p> <p>0.45 5 8 1.2 8.92</p> <p>Note the arrangement of circuit patterns</p>

Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface).
A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)		A (°C) 3s max.	B (°C)	C (s)	D (°C)	E (°C)	F (s)
SSSS2	Vertical 1-pole, 3-position	260	230	40	180	150	120
	Horizontal 1-pole, 2-position 1-pole, 3-position 2-pole, 3-position						
	Vertical 1-pole, 2-position						
SSSS7		250					
SSAH, SSAG, SSAJ, SSAL, SSSS8		260					

Notes

1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc. The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SSSF, SSSU	350±10°C	3+1/0s
SSSS2	350±10°C	4s max.
SSSS9	350±10°C	3s max.
SSAH, SSAG, SSAJ, SSAL	350±5°C	3s max.
SSSS8	330±5°C	3s max.
SSSS7	320±5°C	3s max.
SSAC	300±10°C	2s max.

Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SSSS2	100°C max.	60s max.	260±5°C	3±1s
SSSS9	120°C max.	60s max.	260±5°C	5+0/-1s (2 times)
SSSF, SSSU	100°C max.	60s max.	260±5°C	10±1s/5±1s
SSAC	100°C max.	60s max.	260±5°C	5±1s